



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4271-2S		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000723262						
<b>Package</b>		PG-TO220-7-12		<b>Weight*</b>		2154.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.930	0.23	0.23	2289	2289
leadframe	inorganic material	phosphorus	7723-14-0	0.272	0.01		126	
	non noble metal	iron	7439-89-6	0.908	0.04		421	
	non noble metal	copper	7440-50-8	906.793	42.08	42.13	420949	421496
	non noble metal	aluminium	7429-90-5	0.406	0.02	0.02	189	189
wire	non noble metal	aluminium	7429-90-5	0.406	0.02	0.02	189	189
encapsulation	organic material	carbon black	1333-86-4	1.256	0.06		583	
	plastics	epoxy resin	-	57.778	2.68		26822	
	inorganic material	silicondioxide	60676-86-0	568.991	26.41	29.15	264136	291541
leadfinish	non noble metal	tin	7440-31-5	23.005	1.07	1.07	10680	10680
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	100	101
solder	non noble metal	tin	7440-31-5	0.120	0.01		56	
	noble metal	silver	7440-22-4	0.151	0.01		70	
	non noble metal	lead	7439-92-1	5.749	0.27	0.29	2669	2795
heatspreader	inorganic material	phosphorus	7723-14-0	0.175	0.01		81	
	non noble metal	iron	7439-89-6	0.584	0.03		271	
	non noble metal	copper	7440-50-8	582.824	27.06	27.10	270557	270909
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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